

← eMMC Based MCP

KMQX10013M-B419

eMMC 32GB + LPDDR3 16Gb with 1600Mbps of eMMC Based MCP

KMQX10013M-B419

OVERVIEW

SPECIFICATIONS

RELATED RESOURCES

MCP (Multi Chip Package) technology allows integration of multiple memory chips of different types, such as NAND flash, eMMC and mobile DRAM, in a single package. MCP-based memory enables the rest of the application to view the memory subsystem as a single, unified "block", letting the memory subsection offer the highest levels of performance for the device. Memory devices designed on the MCP platform are widely used for high-end devices and applications that require the highest storage capacities and data transfer bandwidths in the smallest form factors. Such applications include smartphones and tablet among others.

Along with a substantial reduction in the board space used by the memory subsection, the technique such as die-to-die-bonding and die-to-frame bonding significantly improves the performance of memory devices due to the tight coupling and shortest possible interconnections between the memory chips. Samsung's MCP solutions are the number one choice by designers for deployment on devices such as smartphones, multimedia players, and digital video cameras, among others. They provide the highest memory densities and data transfer bandwidths at the lowest power consumption levels in the smallest form factors.

SPECIFICATIONS

EMMC BASED MCP > KMQX10013M-B419

Production Status	Mass Production	Density	eMMC 32GB(M) + LPDDR3 16Gb
Organization	x8, x32	Speed(Mbps)	1600Mbps
Package	221FBGA	Application	Smartphone

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 - PC DRAM
 - Mobile DRAM
 - Consumer DRAM
 - Graphic DRAM
- Flash Storage
 - V-NAND Technology
- Client SSD
- Enterprise SSD
- eMMC
- UFS
- MCP
 - eMMC Based MCP
 - ePoP

- Exynos Solution
 - ModAP
 - Application Processor
 - Modem/RF
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 - Mobile CIS
 - Industry CIS
- Display Solution
 - Mobile DDI
 - Panel DDI/TCON
- Touch Controller
- Security Solution
 - Smart Card
 - NFC
- Power IC
- Bio-Processor

APPLICATION

- Data Center
 - Web Server
 - Application Server
 - DB Server
 - Storage Server
- Mobile Device
 - Smartphone
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